

IN THE CLAIMS

1. (Currently Amended) An energization processing apparatus for performing, in a reduced-pressure atmosphere, an energization process on electric conductors which are placed on a substrate, comprising:

a vessel which has an exhaust hole and which covers the electric conductors and one region on a surface of the substrate where the electric conductors are placed, to thereby create an airtight atmosphere between the substrate and the vessel;

a first temperature adjusting mechanism for adjusting a temperature of the one region on the surface of the substrate covered with the vessel; and

a second temperature adjusting mechanism for adjusting a temperature of the other another region on the surface of the substrate not covered with the vessel.

2. (Canceled)

3. (Currently Amended) An energization processing method for performing, in a reduced-pressure atmosphere, an energization process on electric conductors which are placed on a substrate, comprising the steps of:

covering the electric conductors and one region on a surface of the substrate where the electric conductors are placed with a vessel which has an exhaust hole, to thereby create an airtight atmosphere between the substrate and the vessel;

reducing a pressure of the airtight atmosphere; and
heating ~~the other~~ another region on the surface of the substrate ~~at a~~
~~temperature higher than the temperature of the one region and energizing the electric~~
~~conductors not covered with the vessel with a heat quantity larger than a heat quantity for~~
~~heating the one region on the surface of the substrate covered with the vessel, to suppress a~~
~~temperature difference between the region covered with the vessel and the region not~~
covered with the vessel.

4. (Cancelled)

5. (New) The energization processing apparatus according to claim 1,
wherein

the first temperature adjusting mechanism has a first thermal
conducting member touching a surface of the substrate just opposite to the one region
covered with the vessel, while the second temperature adjusting mechanism has a second
thermal conducting member touching a surface of the substrate just opposite to the another
region not covered with the vessel.

6. (New) The energization processing apparatus according to claim 1,
wherein

the second temperature adjusting mechanism is capable of thermal generation larger than that of the first temperature adjusting mechanism, to suppress a temperature difference between the one region covered with the vessel and the another region not covered with the vessel.